

MECHANICAL CASE OUTLINE

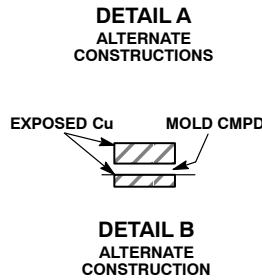
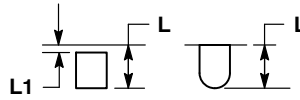
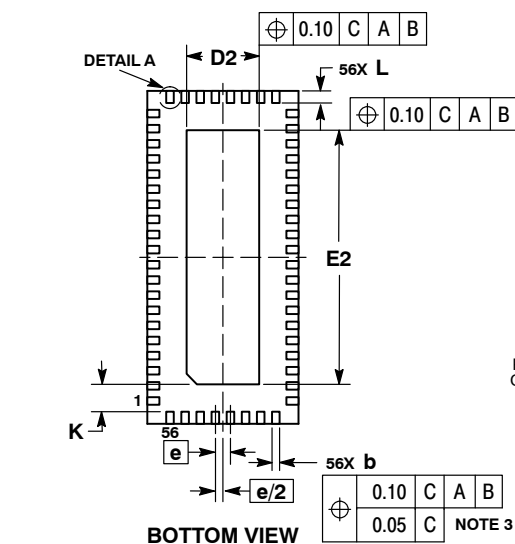
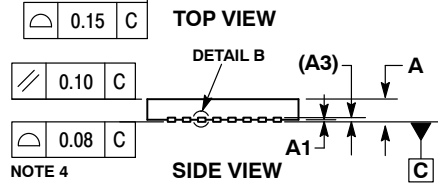
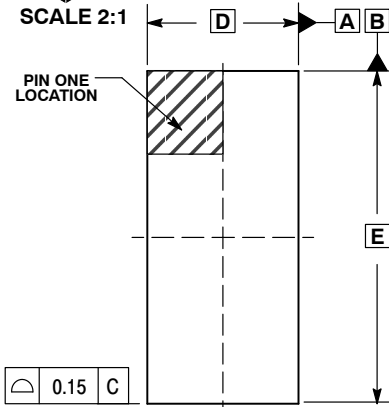
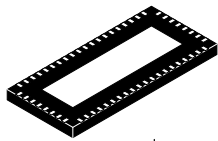
PACKAGE DIMENSIONS

ON Semiconductor®

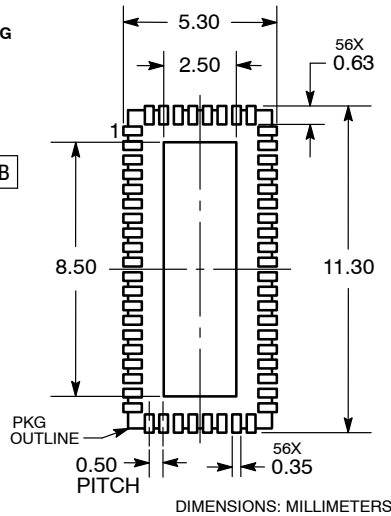


WQFN56 5x11, 0.5P
CASE 510AK-01
ISSUE A

DATE 02 MAR 2010



RECOMMENDED SOLDERING FOOTPRINT

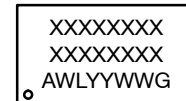


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.70	0.80
A1	---	0.05
A3	0.20	REF
b	0.20	0.30
D	5.00	BSC
D2	2.30	2.50
E	11.00	BSC
E2	8.30	8.50
e	0.50	BSC
K	0.20	MIN
L	0.30	0.50
L1	---	0.15

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

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